

### PSMN1R6-40YLC

N-channel 40 V 1.55 m $\Omega$  logic level MOSFET in LFPAK using NextPower technology

22 August 2012

**Product data sheet** 

### 1. Product profile

#### 1.1 General description

Logic level enhancement mode N-channel MOSFET in LFPAK package. This product is designed and qualified for use in a wide range of industrial, communications and domestic equipment.

#### 1.2 Features and benefits

- High reliability Power SO8 package, qualified to 150°C
- Optimised for 4.5V Gate drive utilising NextPower Superjunction technology
- Ultra low QG, QGD, & QOSS for high system efficiencies at low and high loads
- Ultra low Rdson and low parasitic inductance

### 1.3 Applications

- DC-to-DC converters
- Load switching
- Power OR-ing
- Server power supplies
- Sync rectifier

### 1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V <sub>DS</sub>	drain-source voltage	25 °C ≤ T <sub>j</sub> ≤ 150 °C		-	-	40	V
I <sub>D</sub>	drain current	T <sub>mb</sub> = 25 °C; V <sub>GS</sub> = 10 V; <u>Fig. 1</u>	[1]	-	-	100	Α
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; <u>Fig. 2</u>		-	-	288	W
Tj	junction temperature			-55	-	150	°C
Static charact	eristics						
R <sub>DSon</sub>	drain-source on-state resistance	$V_{GS}$ = 4.5 V; $I_D$ = 25 A; $T_j$ = 25 °C; Fig. 12		-	1.45	1.8	mΩ
		$V_{GS}$ = 10 V; $I_D$ = 25 A; $T_j$ = 25 °C; Fig. 12		-	1.25	1.55	mΩ
Dynamic char	acteristics						
$Q_{GD}$	gate-drain charge	$V_{GS}$ = 4.5 V; $I_D$ = 25 A; $V_{DS}$ = 20 V; Fig. 14		-	15.3	-	nC



Symbol Parameter	Conditions	Min	Тур	Max	Unit
Q <sub>G(tot)</sub> total gate charge	$V_{GS} = 4.5 \text{ V}; I_D = 25 \text{ A}; V_{DS} = 20 \text{ V};$ Fig. 14	-	59	-	nC

[1] Continuous current is limited by package.

### 2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	(000)	D I
2	S	source		
3	S	source		G T T
4	G	gate		mbb076 S
mb	D	mounting base; connected to drain	1 2 3 4	
			LFPAK; Power- SO8 (SOT1023)	

### 3. Ordering information

Table 3. Ordering information

Table 6. Grading III	ioimation						
Type number	Package						
	Name	Description	Version				
PSMN1R6-40YLC	LFPAK; Power-SO8	Plastic single-ended surface-mounted package (LFPAK); 4 leads	SOT1023				

### 4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DS}$	drain-source voltage	25 °C ≤ T <sub>j</sub> ≤ 150 °C		-	40	V
$V_{DGR}$	drain-gate voltage	25 °C ≤ $T_j$ ≤ 150 °C; $R_{GS}$ = 20 kΩ		-	40	V
$V_{GS}$	gate-source voltage			-20	20	V
I <sub>D</sub>	drain current	V <sub>GS</sub> = 10 V; T <sub>mb</sub> = 25 °C; <u>Fig. 1</u>	[1]	-	100	Α
		V <sub>GS</sub> = 10 V; T <sub>mb</sub> = 100 °C; <u>Fig. 1</u>	[1]	-	100	Α
I <sub>DM</sub>	peak drain current	pulsed; $t_p \le 10 \mu s$ ; $T_{mb} = 25 \text{ °C}$ ; Fig. 4		-	1304	Α
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; <u>Fig. 2</u>		-	288	W
T <sub>stg</sub>	storage temperature			-55	150	°C

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Symbol	Parameter	Conditions		Min	Max	Unit
T <sub>j</sub>	junction temperature			-55	150	°C
T <sub>sld(M)</sub>	peak soldering temperature			-	260	°C
V <sub>ESD</sub>	electrostatic discharge voltage	MM (JEDEC JESD22-A115)		1	-	kV
Source-drain	ı diode			'	'	
I <sub>S</sub>	source current	T <sub>mb</sub> = 25 °C	[1]	-	100	Α
I <sub>SM</sub>	peak source current	pulsed; $t_p \le 10 \ \mu s$ ; $T_{mb} = 25 \ ^{\circ}C$		-	1304	Α
Avalanche re	uggedness				'	
E <sub>DS(AL)S</sub>	non-repetitive drain-source avalanche energy	$V_{GS}$ = 10 V; $T_{j(init)}$ = 25 °C; $I_D$ = 100 A; $V_{sup} \le$ 40 V; $R_{GS}$ = 50 Ω; unclamped; Fig. 3		-	391	mJ

#### [1] Continuous current is limited by package.

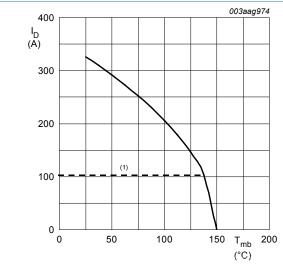


Fig. 1. Continuous drain current as a function of mounting base temperature

 $\label{eq:VGS} V_{\textit{GS}}\!\geq\!10\,V$  (1) Capped at 100 A due to package.

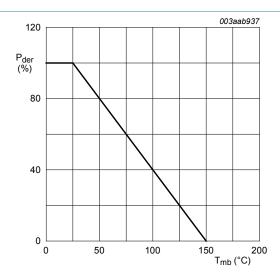


Fig. 2. Normalized total power dissipation as a function of solder point temperature

$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\%$$

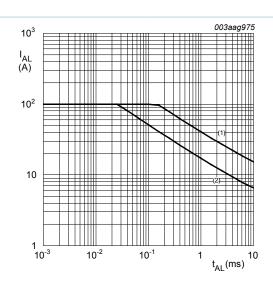


Fig. 3. Single pulse avalanche rating; avalanche current as a function of avalanche time

(1) 
$$T_{j (init)} = 25$$
°C; (2)  $T_{j (init)} = 100$ °C

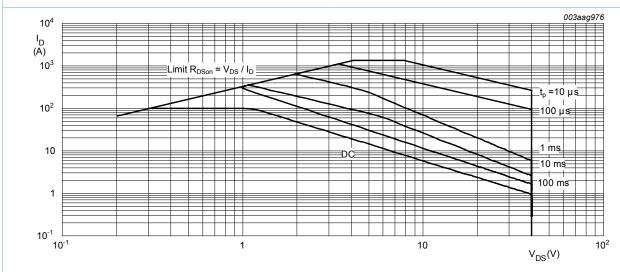


Fig. 4. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

$$T_{mb} = 25^{\circ}C$$
;  $I_{DM}$  is a single pulse

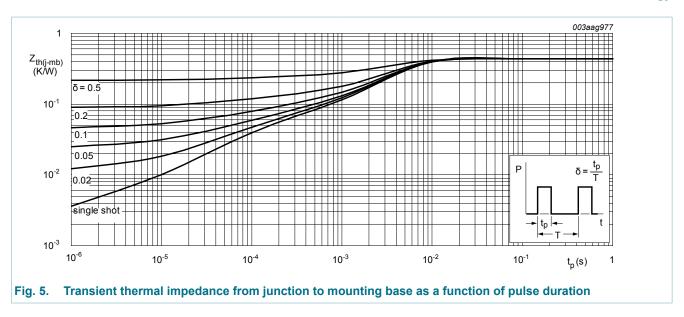
### 5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	Fig. 5	-	0.35	0.43	K/W

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### 6. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
Static chara	acteristics					,	
$V_{(BR)DSS}$	drain-source	$I_D = 250 \mu A; V_{GS} = 0 V; T_j = 25 °C$	40	-	-	V	
	breakdown voltage	$I_D = 250 \mu A; V_{GS} = 0 V; T_j = -55 °C$	36	-	-	V	
V <sub>GS(th)</sub> gate-source voltage	gate-source threshold voltage	I <sub>D</sub> = 1 mA; V <sub>DS</sub> = V <sub>GS</sub> ; T <sub>j</sub> = 25 °C; Fig. 10; Fig. 11	1.05	1.46	1.95	V	
		$I_D = 10 \text{ mA}; V_{DS} = V_{GS}; T_j = 150 \text{ °C}$	0.5	-	-	V	
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ °C}$	-	-	2.25	V	
I <sub>DSS</sub> drain leakage current	V <sub>DS</sub> = 40 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	1	μA		
	V <sub>DS</sub> = 40 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 150 °C	-	-	100	μΑ		
I <sub>GSS</sub> gate leakage current	gate leakage current	V <sub>GS</sub> = 16 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	100	nA	
		V <sub>GS</sub> = -16 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	100	nA	
R <sub>DSon</sub>	drain-source on-state resistance	$V_{GS}$ = 4.5 V; $I_D$ = 25 A; $T_j$ = 25 °C; Fig. 12	-	1.45	1.8	mΩ	
			V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 150 °C; Fig. 12; Fig. 13	-	-	3.2	mΩ
		V <sub>GS</sub> = 10 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 25 °C; Fig. 12	-	1.25	1.55	mΩ	
		V <sub>GS</sub> = 10 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 150 °C; Fig. 12; Fig. 13	-	-	2.7	mΩ	
R <sub>G</sub>	gate resistance	f = 1 MHz	-	1.17	2.34	Ω	

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Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Dynamic ch	naracteristics					,
Q <sub>G(tot)</sub>	total gate charge	I <sub>D</sub> = 25 A; V <sub>DS</sub> = 20 V; V <sub>GS</sub> = 10 V; Fig. 14; Fig. 15	-	126	-	nC
		I <sub>D</sub> = 25 A; V <sub>DS</sub> = 20 V; V <sub>GS</sub> = 4.5 V; Fig. 14	-	59	-	nC
		I <sub>D</sub> = 0 A; V <sub>DS</sub> = 0 V; V <sub>GS</sub> = 10 V	-	115	-	nC
$Q_{GS}$	gate-source charge	$I_D = 25 \text{ A}; V_{DS} = 20 \text{ V}; V_{GS} = 4.5 \text{ V};$	-	17.7	-	nC
Q <sub>GS(th)</sub>	pre-threshold gate- source charge	Fig. 14	-	12.5	-	nC
Q <sub>GS(th-pl)</sub>	post-threshold gate- source charge		-	5.2	-	nC
$Q_{GD}$	gate-drain charge		-	15.3	-	nC
$V_{GS(pl)}$	gate-source plateau voltage	I <sub>D</sub> = 25 A; V <sub>DS</sub> = 20 V; <u>Fig. 14</u>	-	2.4	-	V
C <sub>iss</sub>	input capacitance	V <sub>DS</sub> = 20 V; V <sub>GS</sub> = 0 V; f = 1 MHz;	-	7790	-	pF
C <sub>oss</sub>	output capacitance	T <sub>j</sub> = 25 °C; <u>Fig. 16</u>	-	1063	-	pF
C <sub>rss</sub>	reverse transfer capacitance		-	409	-	pF
t <sub>d(on)</sub>	turn-on delay time	$V_{DS}$ = 20 V; $R_L$ = 0.8 $\Omega$ ; $V_{GS}$ = 4.5 V;	-	41	-	ns
t <sub>r</sub>	rise time	$R_{G(ext)} = 4.7 \Omega$	-	48	-	ns
t <sub>d(off)</sub>	turn-off delay time		-	86	-	ns
t <sub>f</sub>	fall time		-	42	-	ns
Q <sub>oss</sub>	output charge	$V_{GS} = 0 \text{ V}; V_{DS} = 20 \text{ V}; f = 1 \text{ MHz};$ $T_j = 25 \text{ °C}$	-	38.7	-	nC
Source-drai	in diode					
$V_{SD}$	source-drain voltage	$I_S = 25 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C}; Fig. 17$	-	0.77	1.1	V
t <sub>rr</sub>	reverse recovery time	$I_S$ = 25 A; $dI_S/dt$ = -100 A/ $\mu$ s; $V_{GS}$ = 0 V; $V_{DS}$ = 20 V; <u>Fig. 18</u>	-	44	-	ns
Q <sub>r</sub>	recovered charge	$I_S$ = 25 A; $dI_S/dt$ = -100 A/ $\mu$ s; $V_{GS}$ = 0 V; $V_{DS}$ = 20 V	-	62	-	nC
t <sub>a</sub>	reverse recovery rise time	$V_{GS} = 0 \text{ V}; I_S = 25 \text{ A}; dI_S/dt = -100 \text{ A/}\mu\text{s};$ $V_{DS} = 20 \text{ V}; Fig. 18$	-	26	-	ns
t <sub>b</sub>	reverse recovery fall time		-	18	-	ns

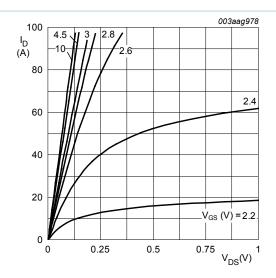


Fig. 6. Output characteristics; drain current as a function of drain-source voltage; typical values



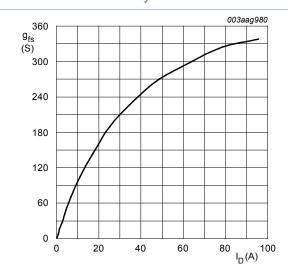


Fig. 8. Forward transconductance as a function of drain current; typical values

$$T_j = 25^{\circ}C; \ V_{DS} = 10V$$

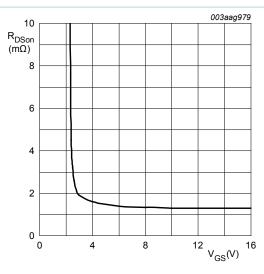


Fig. 7. Drain-source on-state resistance as a function of gate-source voltage; typical values

$$T_j = 25$$
°C;  $I_D = 25$ A

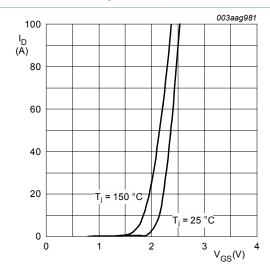


Fig. 9. Transfer characteristics; drain current as a function of gate-source voltage; typical values

$$V_{DS} = 10V$$

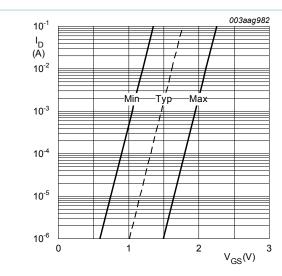


Fig. 10. Sub-threshold drain current as a function of gate-source voltage

$$T_j = 25^{\circ}C; \ V_{DS} = 5V$$

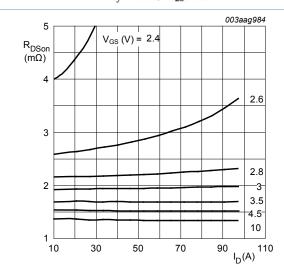


Fig. 12. Drain-source on-state resistance as a function of drain current; typical values

$$T_j = 25^{\circ}C$$

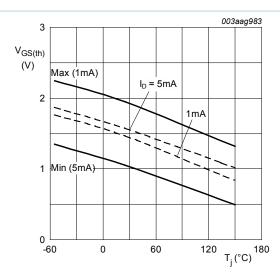


Fig. 11. Gate-source threshold voltage as a function of junction temperature

$$V_{DS} = V_{GS}$$

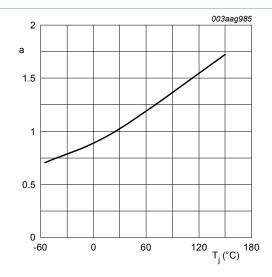


Fig. 13. Normalized drain-source on-state resistance factor as a function of junction temperature

$$a = \frac{R_{DSon}}{R_{DSon (25^{\circ}\text{C})}}; V_{GS} \leq 10V$$

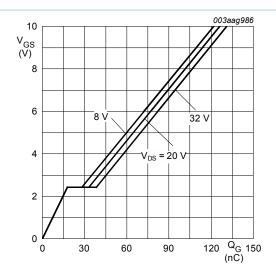
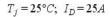


Fig. 14. Gate-source voltage as a function of gate charge; typical values



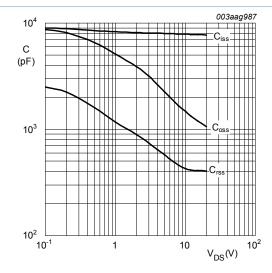


Fig. 16. Input, output and reverse transfer capacitances | Fig. 17. Source current as a function of source-drain as a function of drain-source voltage; typical values

$$V_{GS} = \mathbf{0}V; \ f = \mathbf{1}MHz$$

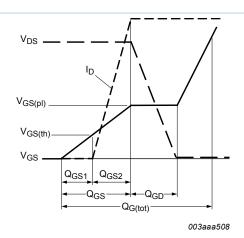
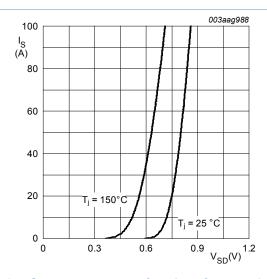
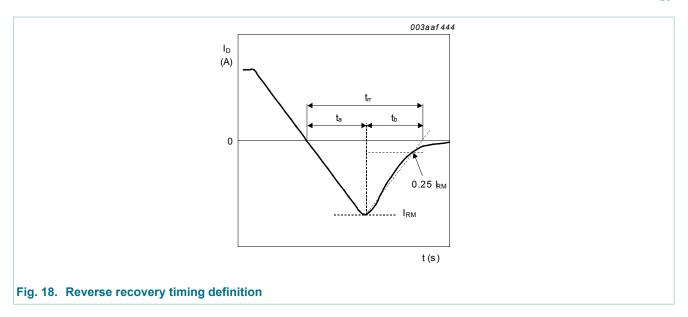


Fig. 15. Gate charge waveform definitions

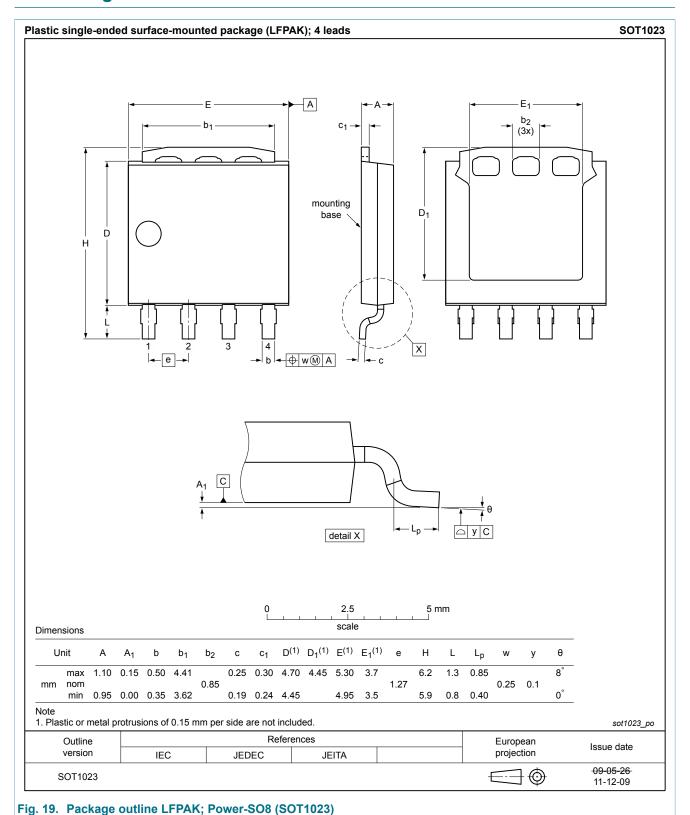


voltage; typical values

$$V_{GS} = 0V$$



### 7. Package outline



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### 8. Legal information

#### 8.1 Data sheet status

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